

Title (en)

LIQUID COOLING SYSTEM FOR AN ELECTRONIC SYSTEM

Title (de)

FLÜSSIGKEITSKÜHLSYSTEM FÜR EIN ELEKTRONISCHES SYSTEM

Title (fr)

SYSTÈME DE REFROIDISSEMENT LIQUIDE POUR UN SYSTÈME ÉLECTRONIQUE

Publication

EP 2633378 A1 20130904 (EN)

Application

EP 10805292 A 20101028

Priority

IB 2010002906 W 20101028

Abstract (en)

[origin: WO2012056261A1] A liquid cooling system for an electronic system includes a plurality of cooling modules that are adapted to circulate a liquid coolant therethrough. Each cooling module is configured to be coupled to a circuit board of the electronic system and placed in thermal contact with one of a plurality of heat-generating electronic components on the circuit board. The cooling system also includes a plurality of heat exchangers that are configured to dissipate heat from the liquid coolant to air. Each heat exchanger of the plurality of heat exchangers is fluidly coupled between two cooling modules of the plurality of cooling modules in a flow path of the liquid. The cooling system also includes a plurality of conduits that fluidly couple the plurality of cooling modules to the plurality of heat exchangers.

IPC 8 full level

G06F 1/20 (2006.01)

CPC (source: EP)

G06F 1/203 (2013.01); **G06F 2200/201** (2013.01)

Citation (search report)

See references of WO 2012056261A1

Citation (examination)

- EP 1883287 A1 20080130 - FUJITSU LTD [JP]
- US 2007012423 A1 20070118 - KINOSHITA KOICHIRO [JP], et al

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

WO 2012056261 A1 20120503; EP 2633378 A1 20130904

DOCDB simple family (application)

IB 2010002906 W 20101028; EP 10805292 A 20101028